

RELIABILITY REPORT  
FOR  
MAX8214AESE+  
PLASTIC ENCAPSULATED DEVICES

July 31, 2015

**MAXIM INTEGRATED**

160 RIO ROBLES  
SAN JOSE, CA 95134

<b>Approved by</b>
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**Conclusion**

The MAX8214AESE+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

**Table of Contents**

<b>I. ....Device Description</b>	<b>IV. ....Die Information</b>
<b>II. ....Manufacturing Information</b>	<b>V. ....Quality Assurance Information</b>
<b>III. ....Packaging Information</b>	<b>VI. ....Reliability Evaluation</b>
<b>.....Attachments</b>	

**I. Device Description**

## A. General

The MAX8213 and MAX8214 contain four precision voltage comparators capable of monitoring undervoltage and overvoltage conditions for both positive and negative supplies. Accurate trip-point setting is facilitated by the internal 1.25V reference. Not only is trip-level accuracy guaranteed to  $\pm 1\%$  over the commercial temperature range, but the trip levels of all channels are guaranteed to match each other within  $\pm 1\%$ . A fifth comparator channel monitors microprocessor voltages and generates delayed reset signals. The MAX8213 has open-drain outputs, while active pull-up outputs are incorporated in the MAX8214.

## II. Manufacturing Information

A. Description/Function:	Five Universal Voltage Monitors, Complete $\mu$ P Voltage Monitoring
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	Pre 1997

## III. Packaging Information

A. Package Type:	16-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1701-0057
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	115°C/W
K. Single Layer Theta Jc:	32°C/W
L. Multi Layer Theta Ja:	75°C/W
M. Multi Layer Theta Jc:	24°C/W

## IV. Die Information

A. Dimensions:	66X76 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	$\text{SiO}_2$
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)  
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% for all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 397 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 9.39 \times 10^{-9}$$

$$\lambda = 9.39 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.03 @ 25C and 0.03 @ 55C (0.8 eV, 60% UCL)

### B. E.S.D. and Latch-Up Testing (ESD lot XAGBDA004A D/C 9246, Latch-Up NAGBHA130A D/C 0528)

The PW14-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-400V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

**Table 1**  
Reliability Evaluation Test Results

## MAX8214AESE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)	Ta = 135°C	DC Parameters & functionality	77	0	NAGBFO003
	Biased		80	2	BAGAEX001A
	Time = 192 hrs.		80	0	XAGACB001A
			80	0	XAGBCY001B
			80	0	XAGBDA004A

Note 1: Life Test Data may represent plastic DIP qualification lots.